US00D774479S

(12) United States Design Patent

Soyano et al.

(10) Patent No.: US D774,479 S
(45) Date of Patent: ** Dec. 20, 2016

(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/528,214**

(22) Filed: **May 27, 2015**

(30) **Foreign Application Priority Data**

Nov. 28, 2014 (JP) D2014-026634
Nov. 28, 2014 (JP) D2014-026635
Nov. 28, 2014 (JP) D2014-026636

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182
CPC H01L 21/00; H01L 21/02433; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/1905; H01L 29/04; H01L 2224/08054; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262;G02B 6/428; G02B 6/4281; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K

(Continued)

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

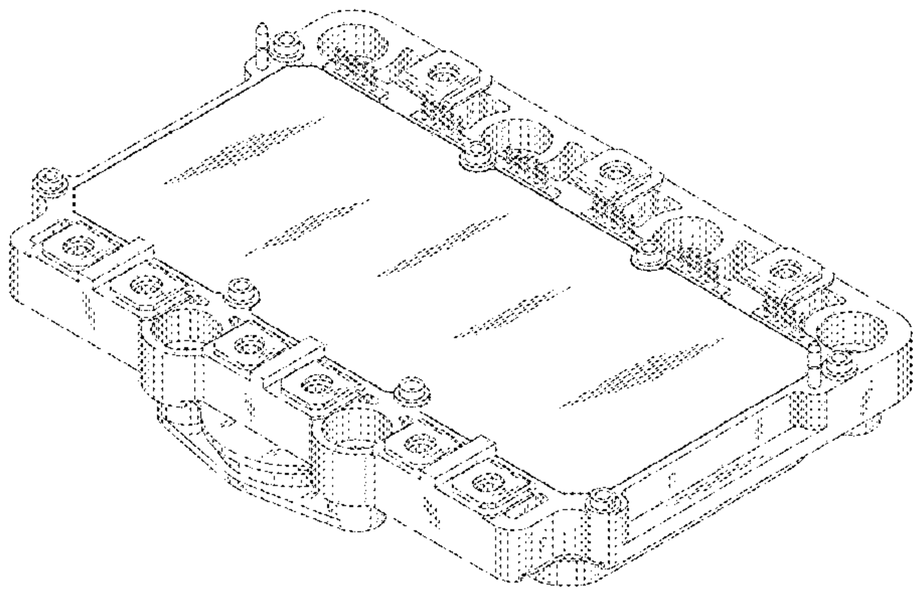
DESCRIPTION

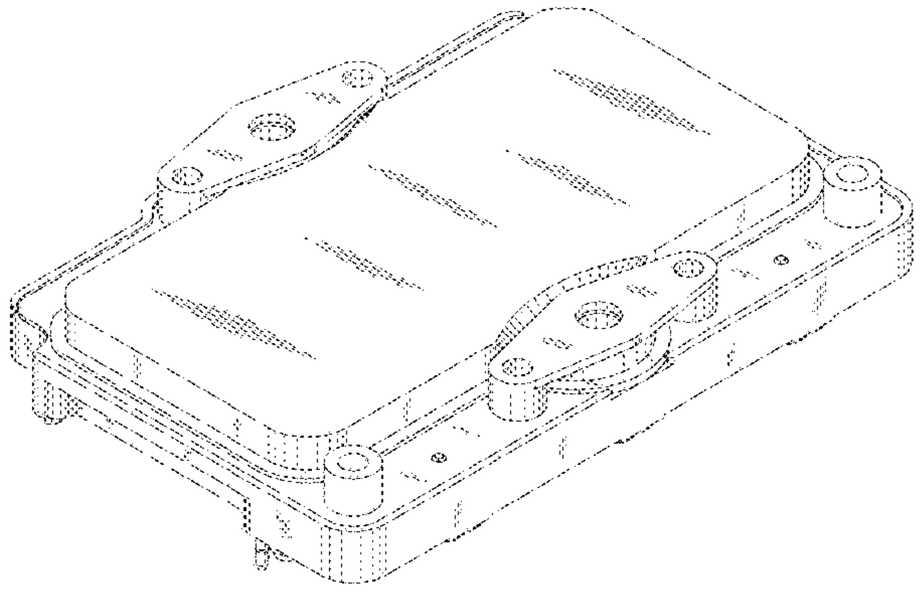
FIG. **1** is a front view of a semiconductor module showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a left side view thereof;
FIG. **4** is a right side view thereof;
FIG. **5** is a top view thereof;
FIG. **6** is a bottom view thereof;
FIG. **7** is a front, right, and bottom perspective view thereof; and,
FIG. **8** is a rear, left, and top perspective view thereof.

The ornamental design of the present disclosure is a semiconductor module on which power semiconductor elements and the like may be mounted. Rhombic plate members having rounded corners are centered along the long sides of the rear view, such that the longer diagonal line of each rhombic plate member extends along a long side.

The broken lines shown in the drawing views of FIGS. **1-8** form no part of the claimed design.

1 Claim, 8 Drawing Sheets





(58) **Field of Classification Search**
CPC 1/18;H05K 1/181; H05K 1/182; H05K 1/026; H05K 1/0228; H05K 1/0245; H05K 1/0236; H05K 1/0263
See application file for complete search history.

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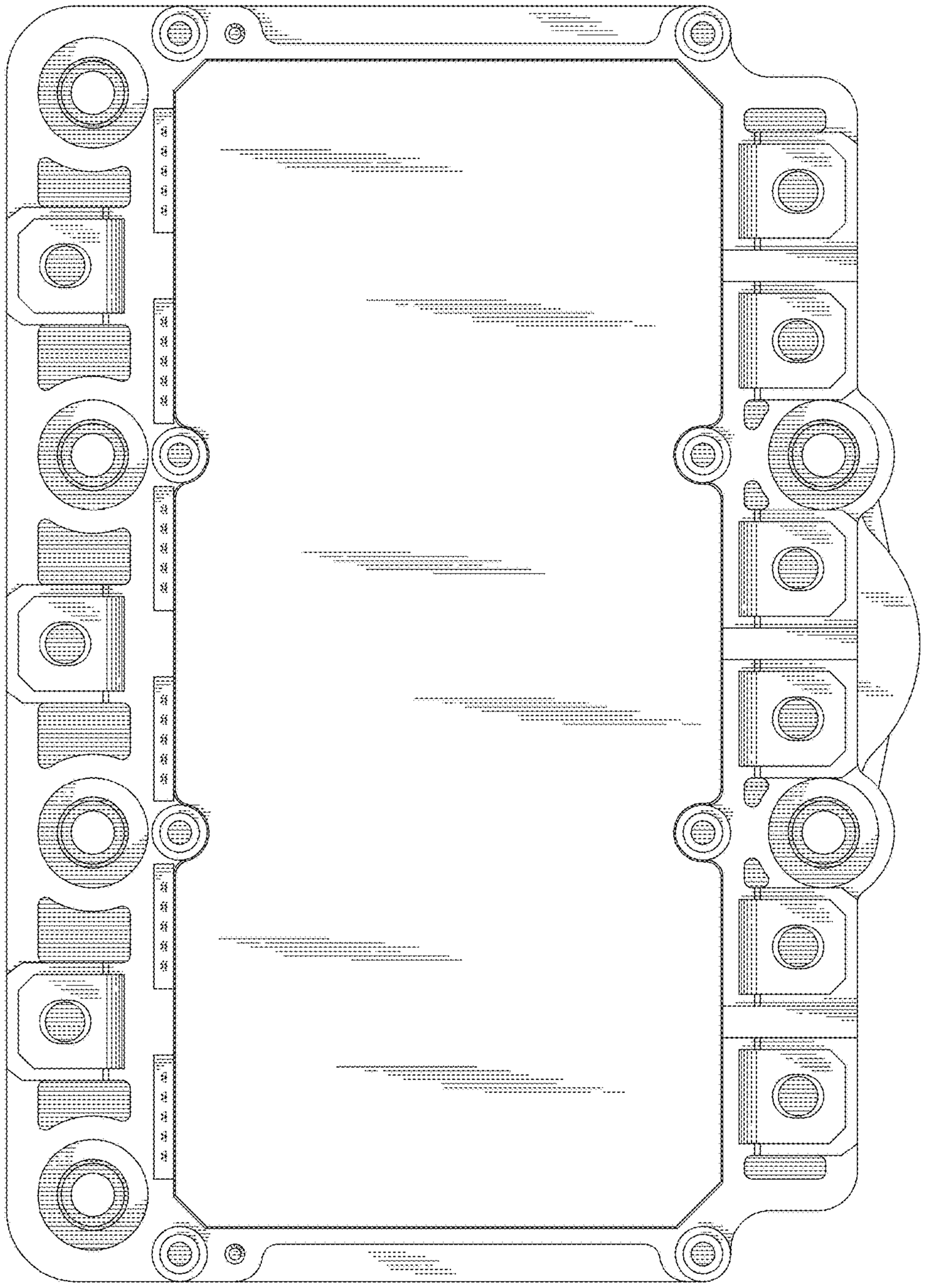


FIG. 1

FIG. 2

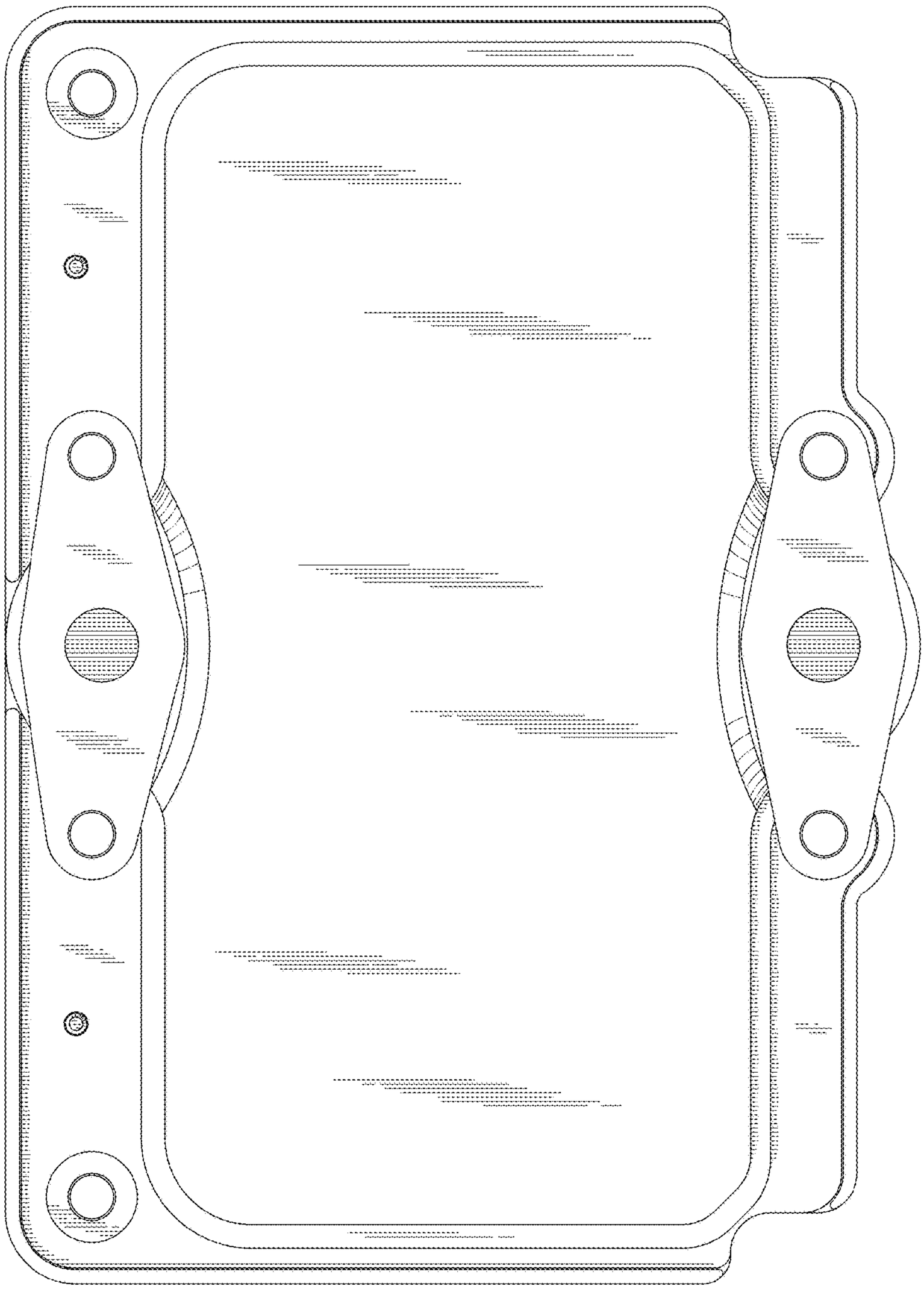


FIG. 3

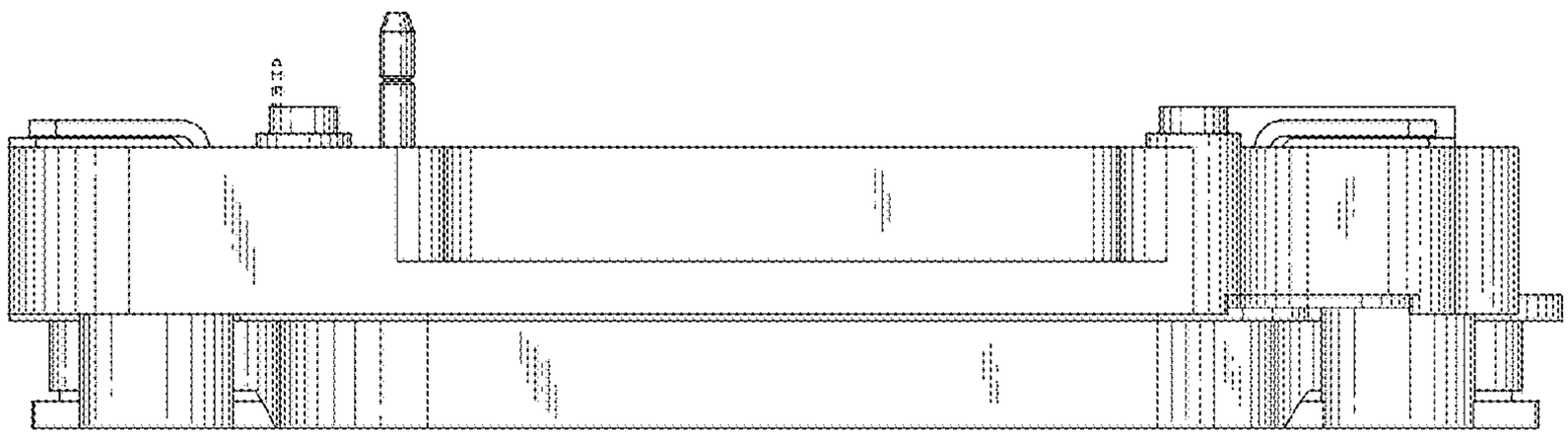
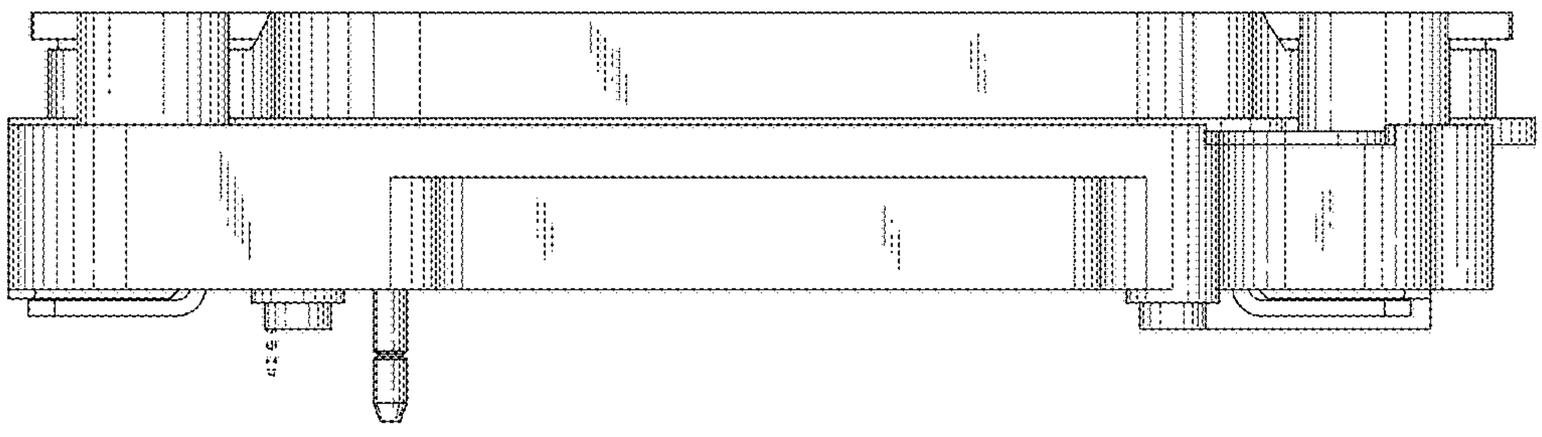


FIG. 4



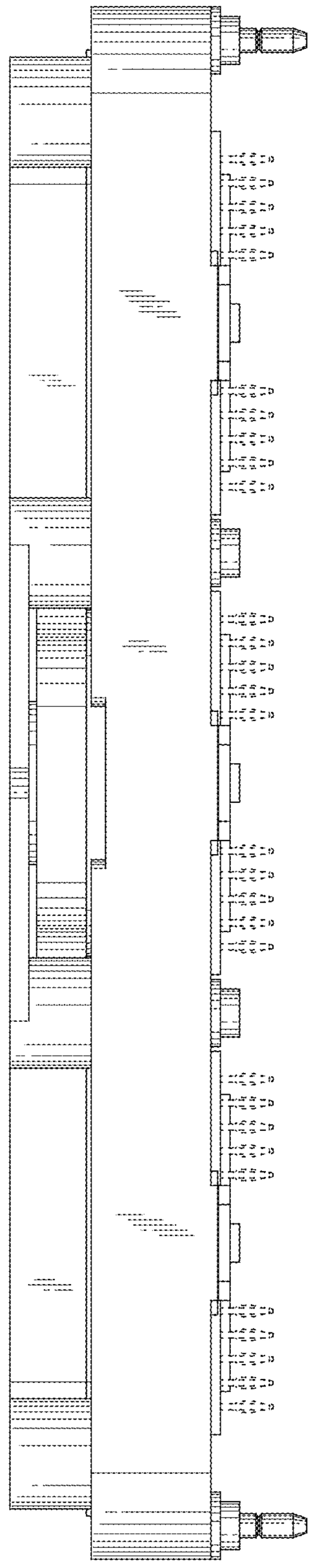


FIG. 5

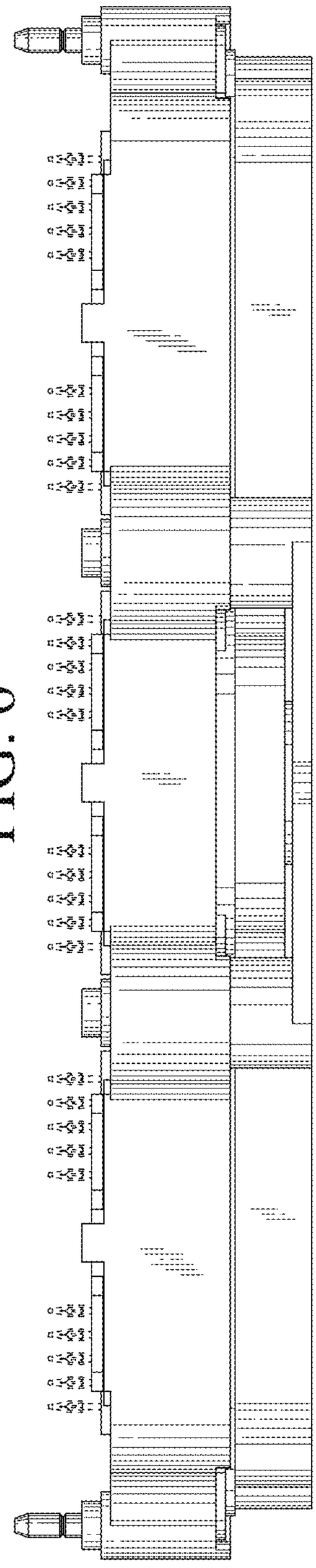


FIG. 6

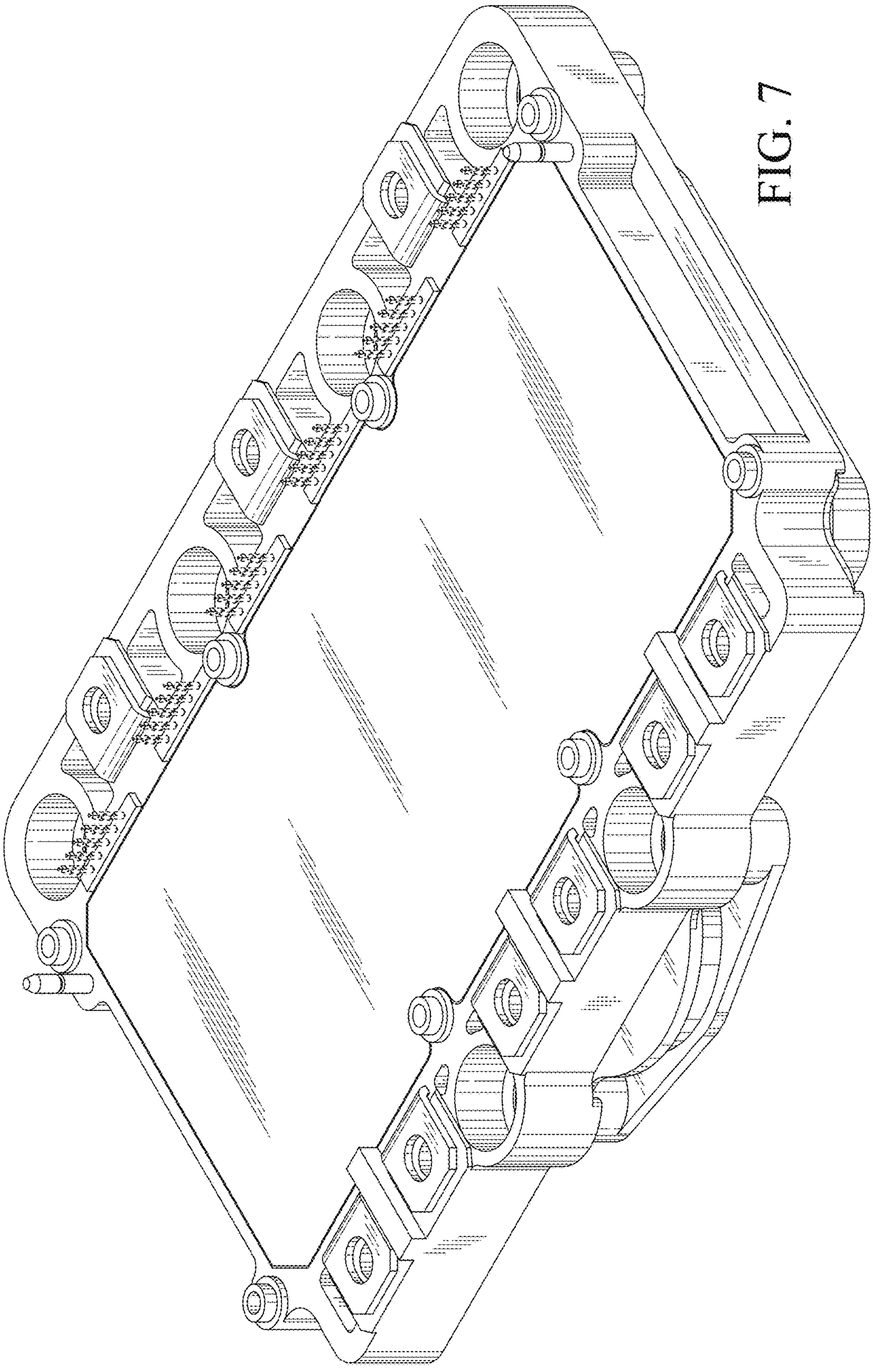


FIG. 7

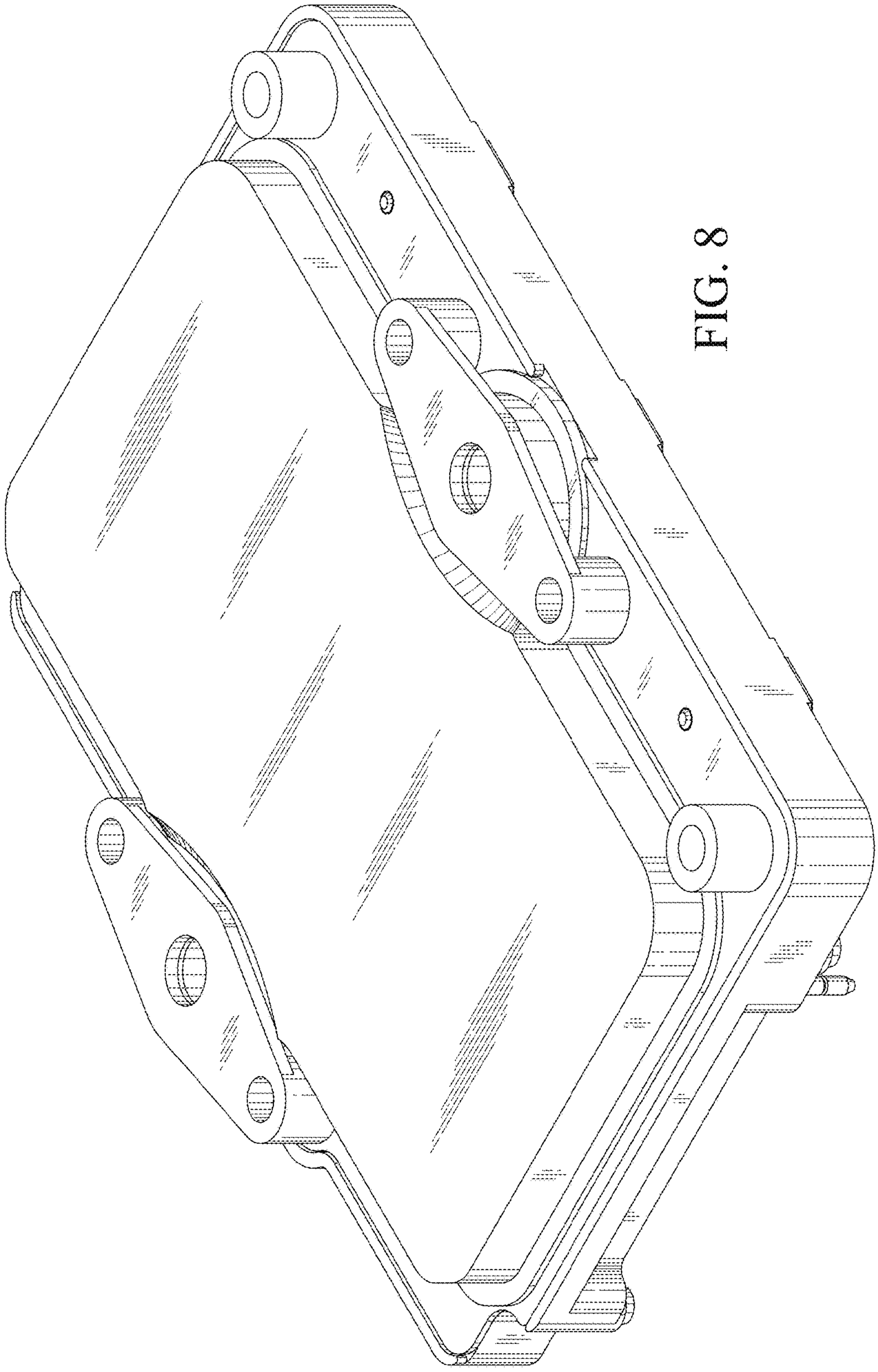


FIG. 8